

What is claimed is:

1. A cleaning solution for cleaning substrates of electronic materials comprising one or more organic acid compounds and at least one selected from the group consisting of dispersants and surfactants.

2. The cleaning solution according to claim 1, wherein the organic acid compound is one or more member(s) selected from the group consisting of oxalic acid, malonic acid, succinic acid, malic acid, tartaric acid, citric acid and ammonium salts thereof.

3. The cleaning solution according to claim 1, wherein the surfactants is an anionic or a nonionic surfactant.

4. The cleaning solution according to claim 1, wherein the dispersant is one or more member(s) selected from the group consisting of condensed phosphoric acids and phosphates.

5. The cleaning solution according to claim 1, wherein the organic acid compound is 0.01 to 30 mass percentages.

6. The cleaning solution according to claim 1, wherein the dispersants and the surfactants are 0.0001 to 10 mass percentages.

7. The cleaning solution according to claim 1, wherein a chelating agent is further comprised.

8. The cleaning solution according to claim 1, wherein a water-soluble alcohol is further comprised.

9. The cleaning solution according to any one of claims 1 to 8, wherein the metallic impurities and the particle contamination adsorbed by a substrate are both removed at the same time.

10. The cleaning solution according to any one of claims 1 to 9, wherein the substrate of electronic materials is a substrate to which metallic wiring has been applied.

11. The cleaning solution according to claim 10, used after
5 chemical mechanical polishing.